Intel Roadmap Overview August 20th 2008

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Agenda

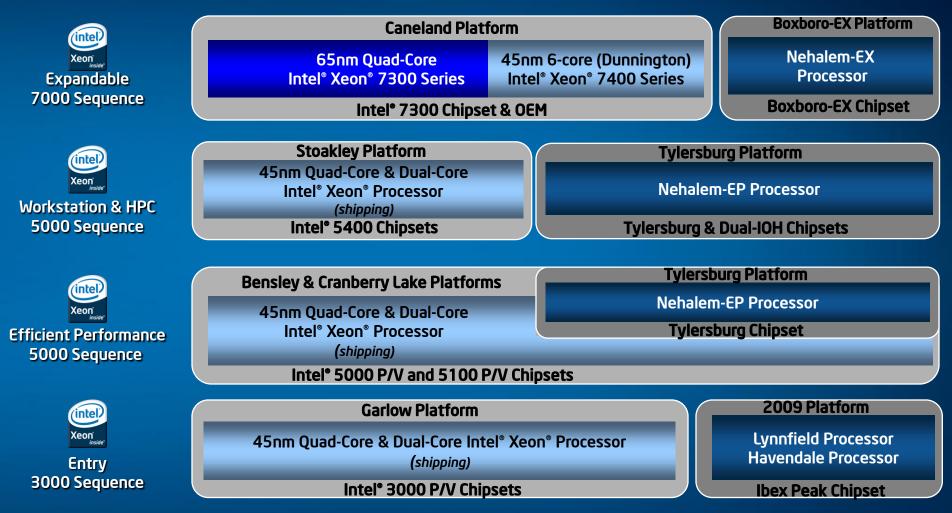
Server Roadmap Client Roadmap Netbook / Nettop Ultra Mobile



Server Products



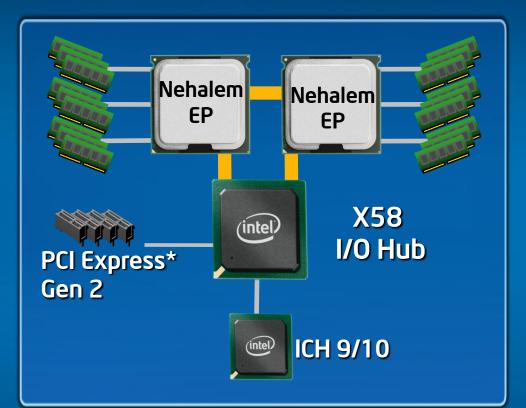
Intel[®] Xeon[®] Enterprise Roadmap 2008* 2009*



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Enterprise: 2008 Nehalem Based Two Socket System Architecture



Intel[®] QuickPath Interconnect

Nehalem-EP Platform:

Two sockets each with Integrated Memory Controller

Turbo mode operation

Intel' QuickPath Architecture

DDR3 Memory: 3 Channel, 3 DIMMs per channel

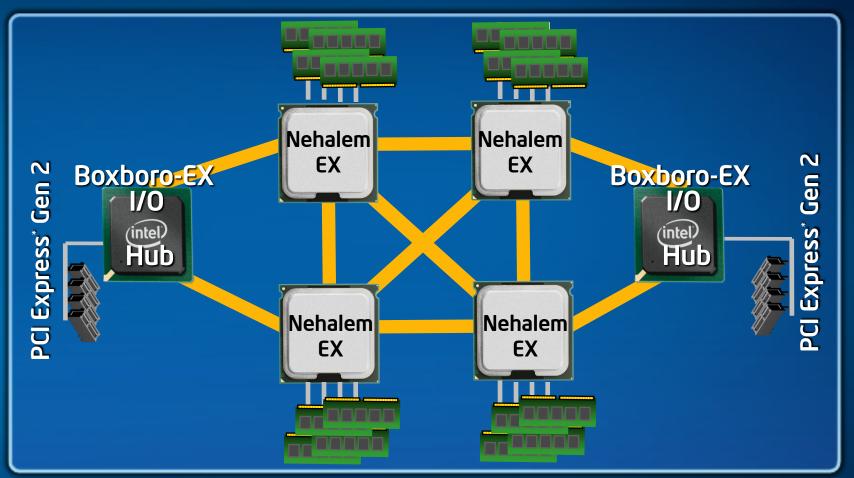
Intel Virtualization Technology

PCI Express* Gen 2

World's Most Adaptable Server Platform



Enterprise: 2009 Nehalem Based Four Socket System Architecture



Boxboro-EX Platform:

Intel[®] QuickPath Interconnect

Four processors with Intel' QuickPath Interconnects PCI Express⁻ Gen 2, Integrated Memory Controller

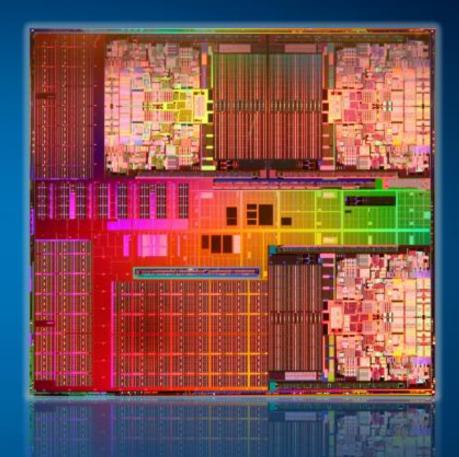


Intel[®] Xeon[®] 7400-based Server Platform Dunnington Extends Caneland Technology Leadership

Latest Intel virtualization capabilities 6 cores,16 MB L3 cache

 4-core/large cache versions available

Socket compatible with Caneland platform 45nm Hi-K technology 1.9 billion transistors Introduction Sep. 2008



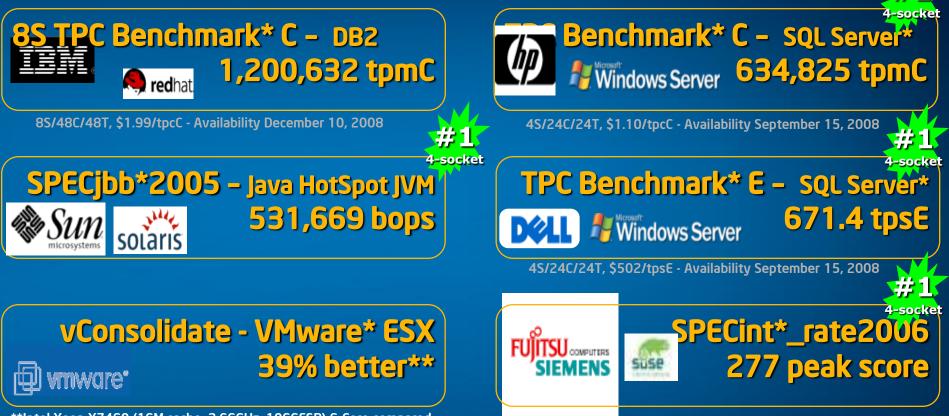
Caneland with Dunnington delivers higher virtualization performance for consolidation and data demanding applications offering more cores, cache and large memory footprint



Intel[®] Xeon[®] 7400 Series (Dunnington) Best-of-class benchmark performance

First 1 million+ TPC-C result for Xeon!





**Intel Xeon X7460 (16M cache, 2.66GHz, 1066FSB) 6-Core compared to Intel Xeon X7350 (4M cache, 2.93GHz, 1066FSB) Quad-Core.

Expandable Server Leadership



Client Products



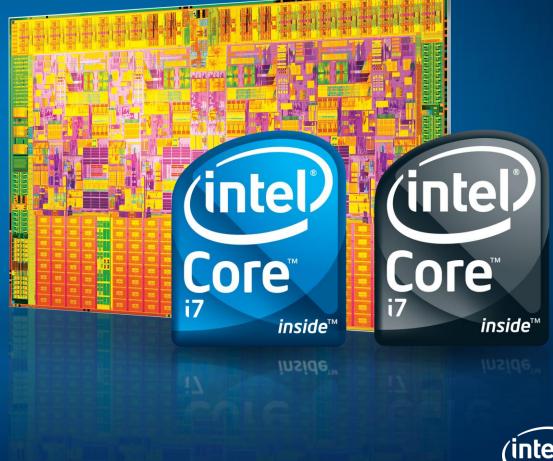
Intel Notebook / Desktop Roadmap		
	2008*	2009*
Desktop Extreme / High-End Desktop	2007 and 2008 Desktop Platforms 45nm Intel® Core™2 Extreme proc. 45nm Intel® Core™2 Quad proc. (shipping) Intel® X48, X38, P45, and P35 Chipsets	X58 Platform Intel® Core i7 Extreme Processor (4C/8T) Intel® Core i7 Processor (4C/8T) Intel® X58 Express Chipset
Desktop Performance / Mainstream	2007 & 2008 Desktop Platforms 45nm Intel® Core™2 Quad and Duo proce (shipping) Intel® 3 and 4 Series Chipsets	Piketon / Kings Creek Platforms Lynnfield (4C/8T) Havendale (2C/4T) Ibex Peak
Mobile Extreme	Santa Rosa & Montevina Platforms 45nm Mobile Intel® Core™2 Extreme proce (Dual-Core shipping today, Quad-Core Q3'08 Intel® 96x and 4 Series Chipsets	essors Clarksfield Processor (4C/8T)
Mobile Performance / Mainstroom	Santa Rosa & Montevina Platforms 45nm Intel® Core™2 Duo processors (shipping)	Calpella Platform Clarksfield (4C/8T) Auburndale (2C/4T) Ibex Peak-M
Mainstream Intel [®] 96x and 4 Series Chipsets		
Nehalem Drives Next Wave of Leadership in the Client All products, dates, and programs are based on current expectations and subject to change without notice.		

without notice. Timeline refers to Intel component production dates

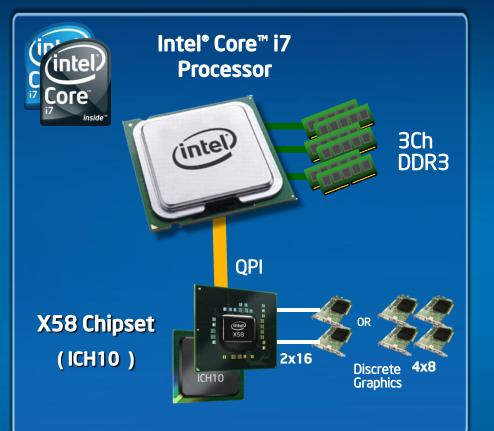
INTRODUCING

NEW INTEL[®] CORE[™] PROCESSOR FAMILY

Intel's Most Advanced Processors Ever!



2008 Nehalem Desktop Platform



Intel[®] Hyper-Threading Technology

- 4 cores, 8 threads

Turbo mode enabled

8M Intel[®] Smart Cache

Intel[®] QuickPath Interconnect

Extreme SKU has overspeed protection removed for overclocking¹

Integrated Memory Controller

- 3 Channels of DDR3 Memory
- 2 DIMMs per channel

Dual x16 PCI Express* Gen 2 configurable as quad x8

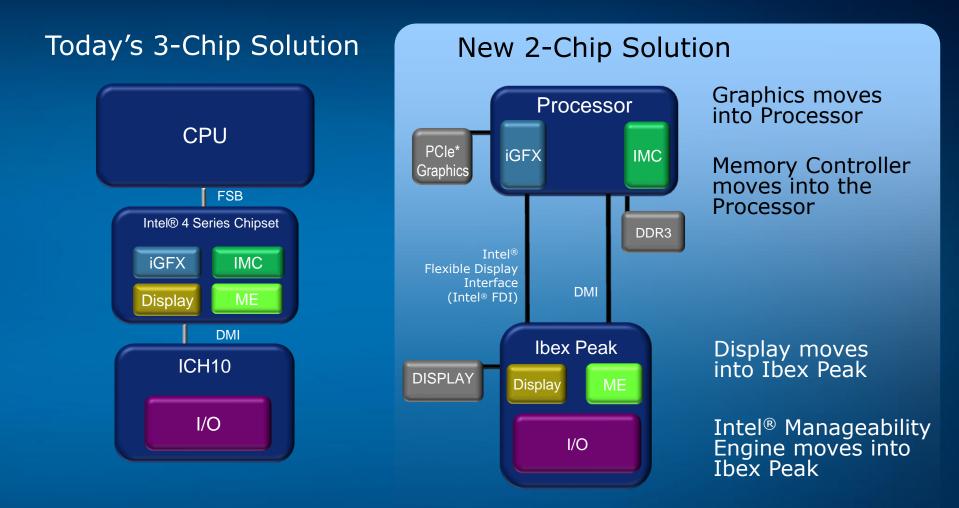
Intel QuickPath Interconnect

The Intel[®] Core[™] i7 Desktop Platform Architecture Delivers New Levels of Performance and Bandwidth

¹Warning: Altering clock frequency and/or voltage may (i) reduce system stability and useful life of the system and processor; (ii) cause the processor and other system components to fail; (iii) cause reductions in system performance; (iv) cause additional heat or other damage; and (v) affect system data integrity. Intel has not tested, and does not warranty, the operation of the processor beyond its specifications.



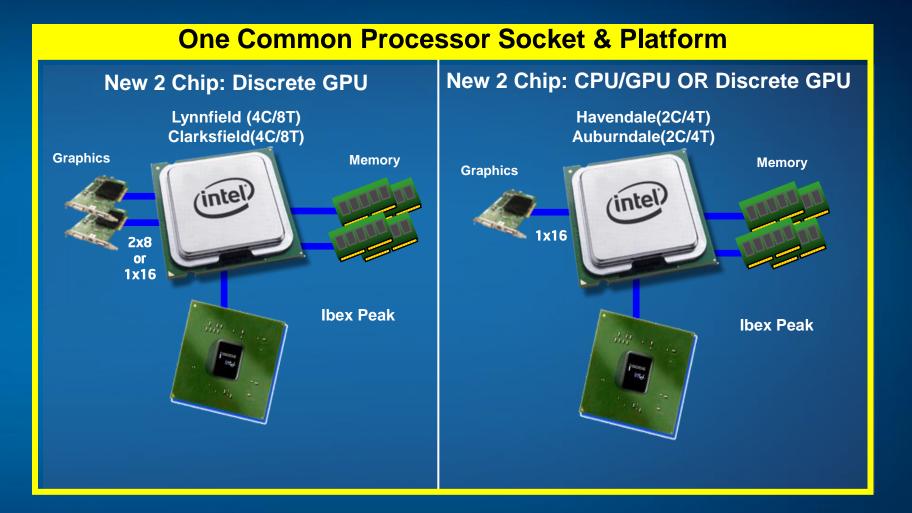
Mainstream Client Platform Partitioning



Smaller boards, lower power, simplified power delivery

Greater performance via higher integration (igfx/IMC)

2009 Mainstream Client Processors





Netbook / Nettop



A New Category of Devices

Want the "Best Internet Experience in Your Pocket"?

> Get a Mobile Internet Device

MID: Infotainment, On The Go Want a Simple Device for Internet Use?

> Get a Netbook or Nettop

> > Internet use

Target SPP Netbook: ~\$249-349 Nettop: ~\$199-299 Want a Richer, Fuller Experience?

> Get a Notebook or Desktop

Entertainment, Productivity and Multitasking



*Other brand and names are the property of their respective owners

intel

inside

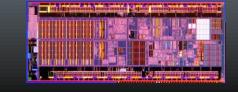
Atom

Nettop / Netbook Roadmap



2007 Celeron 220 65nm Low Cost Purpose Built Platform

inte Atom inside 2008 Intel[®] Atom 45nm **Nettop Solutions Lower Power** Lower Cost Single and Dual Core Solutions



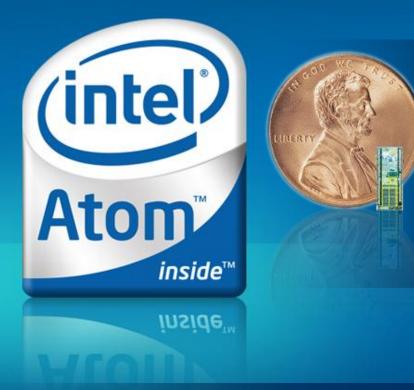


2009+ Continued innovation at the silicon and platform level



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For Netbook and Nettop Platforms Intel[®] Atom[™] Processor Based Platform



New low-power architecture designed from the ground up to enable simple, purpose-built devices for the Internet
Manufactured using Intel's industryleading Hi-K Metal Gate 45nm process technology

- Single core and Dual core proc*
- With Intel[®]945GC and 945GSE chipsets
- 50+ 0EM & 0DM design wins



Available Today!

* DC on Nettop only

Ultra Mobile



Ultra Mobile Roadmap

MOORESTOWN

nte



45nm Silverthorne and Poulsbo Responsive Internet Experience

First Grounds Up Low Power CPU and Chipset 2009/2010

45nm

Projected >10X Reduction In Idle Power Compared to 2008 Platform

First Entry Into Phone Form Factors



Future

32nm

Higher Levels Of Integration

Continued Benefits From Leading Edge Process



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Thanks

Q & A

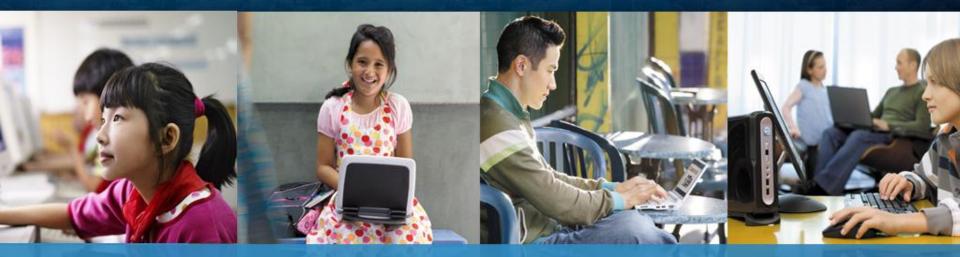


Intel's Tick Tock Development Model





Significant Market Opportunity For Netbooks and Nettops



Emerging Markets

Majority of households surveyed in emerging markets have zero PCs

Opportunity: First time buyer, primary device

Mature Markets

Minority of households surveyed in mature markets have > 1 PC

Opportunity: Nth time buyer, secondary device

Segment expected to grow to over 100Mu by 2011



*Survey limited to major cities in Emerging Markets and do not represent all emerging market populations

Source: 2004-2006 Intel Consumer Tech Metrics Overview; Q4 2006 Results; Mercury Research, Jan 2008; Gartner Quarterly, Dec 2007; IDC Research, Dec 2007

Client: $2008 \rightarrow 2009$ Desktop Transition 2008 2009 Core i7 Extreme Extreme Intel® Core i7 (4c/8T) Core i7 Performance Intel[®] X58 Lynnfield (4C/8T) Core i7 **Nehalem Based** Havendale (2C/4T) **Ibex Peak** Mainstream **Nehalem Based** Q9000 and E8000 Series **Core Micro-architecture on 45nm Core Micro-architecture on 45nm** Value Higher Integration Integrated Board Solution Diamondville Basic **Integrated Board Solution**

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